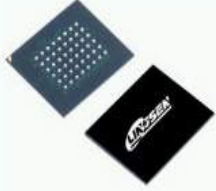


# Data Sheet - WFBGA

## DESCRIPTION



Lingsen' WFBGA (Very-Very Fine Ball Grid Array) is the thinner package solution for mobile applications, All non-Pb (lead-free) devices are RoHS compliant

## APPLICATIONS

- Memory Storage
- Logic

## FEATURES

- Thinner package height achieved 0.63mm typical
- Smaller ball size 0.3mm
- Memory density to 64M

## SPECIFICATIONS

Substrate: BT

Solder ball: Sn96.5/Ag3/Cu0.5

Au Wire: 99%.

Molding Compound: G770HT

Die attached: DAF

Marking: Laser.

Packing: Tray.

## PACKAGE AVAILABILITY

Package Size (mm)	Ball Pitch (mm)	Ball Count
6.0x4.0	0.5	34
6.0x4.0	0.5	48
6.0x5.0	0.5	48

## RELIABILITY

Temperature Cycling                    -65°C/150°C, 500 cycles.

# Data Sheet - WFBGA

## THERMAL PERFORMANCE

Package	Body size (mm)	Gate size ( $\mu\text{m}$ )	Die size (mm)	Thermal Performance $\psi_{ja}$ ( $^{\circ}\text{C}/\text{W}$ )
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## ELECTRICAL PERFORMANCE

Package	Body size (mm)	Gate size ( $\mu\text{m}$ )	Frequency (MHz)	Self inductance (nH)	Self capacitance (pF)	Resistance (mohm)
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## CROSS-SECTION

